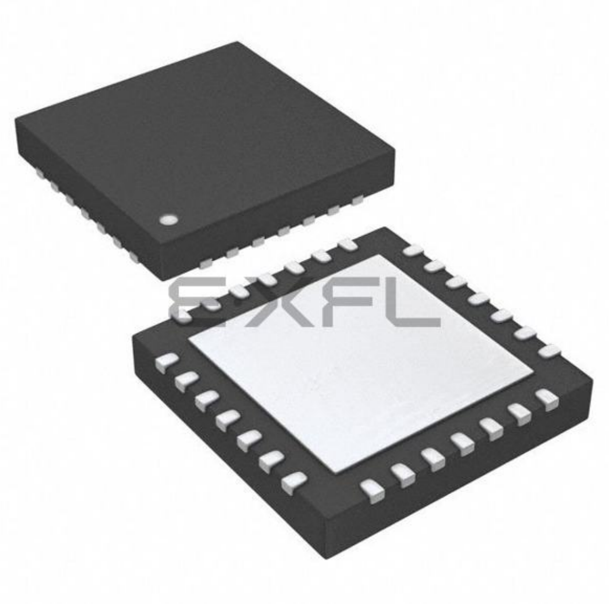

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	16
Program Memory Size	4KB (2K x 16)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf1230-i-ml

4.4.3 RC_IDLE MODE

In RC_IDLE mode, the CPU is disabled but the peripherals continue to be clocked from the internal oscillator block using the INTOSC multiplexer. This mode allows for controllable power conservation during Idle periods.

From RC_RUN, this mode is entered by setting the IDLEN bit and executing a SLEEP instruction. If the device is in another Run mode, first set IDLEN, then set the SCS1 bit and execute SLEEP. Although its value is ignored, it is recommended that SCS0 also be cleared; this is to maintain software compatibility with future devices. The INTOSC multiplexer may be used to select a higher clock frequency by modifying the IRCF bits before executing the SLEEP instruction. When the clock source is switched to the INTOSC multiplexer, the primary oscillator is shut down and the OSTS bit is cleared.

If the IRCF bits are set to any non-zero value, or the INTSRC bit is set, the INTOSC output is enabled. The IOFS bit becomes set, after the INTOSC output becomes stable, after an interval of T_{IOBST} (parameter 39, Table 23-10). Clocks to the peripherals continue while the INTOSC source stabilizes. If the IRCF bits were previously at a non-zero value, or INTSRC was set before the SLEEP instruction was executed and the INTOSC source was already stable, the IOFS bit will remain set. If the IRCF bits and INTSRC are all clear, the INTOSC output will not be enabled, the IOFS bit will remain clear and there will be no indication of the current clock source.

When a wake event occurs, the peripherals continue to be clocked from the INTOSC multiplexer. After a delay of T_{CSD} following the wake event, the CPU begins executing code being clocked by the INTOSC multiplexer. The IDLEN and SCS bits are not affected by the wake-up. The INTRC source will continue to run if either the WDT or the Fail-Safe Clock Monitor is enabled.

4.5 Exiting Idle and Sleep Modes

An exit from Sleep mode or any of the Idle modes is triggered by an interrupt, a Reset or a WDT time-out. This section discusses the triggers that cause exits from power-managed modes. The clocking subsystem actions are discussed in each of the power-managed modes (see **Section 4.2 “Run Modes”, Section 4.3 “Sleep Mode”** and **Section 4.4 “Idle Modes”**).

4.5.1 EXIT BY INTERRUPT

Any of the available interrupt sources can cause the device to exit from an Idle mode or the Sleep mode to a Run mode. To enable this functionality, an interrupt source must be enabled by setting its enable bit in one of the INTCON or PIE registers. The exit sequence is initiated when the corresponding interrupt flag bit is set.

On all exits from Idle or Sleep modes by interrupt, code execution branches to the interrupt vector if the GIE/GIEH bit (INTCON<7>) is set. Otherwise, code execution continues or resumes without branching (see **Section 11.0 “Interrupts”**).

A fixed delay of interval T_{CSD} following the wake event is required when leaving Sleep and Idle modes. This delay is required for the CPU to prepare for execution. Instruction execution resumes on the first clock cycle following this delay.

4.5.2 EXIT BY WDT TIME-OUT

A WDT time-out will cause different actions depending on which power-managed mode the device is in when the time-out occurs.

If the device is not executing code (all Idle modes and Sleep mode), the time-out will result in an exit from the power-managed mode (see **Section 4.2 “Run Modes”** and **Section 4.3 “Sleep Mode”**). If the device is executing code (all Run modes), the time-out will result in a WDT Reset (see **Section 20.2 “Watchdog Timer (WDT)”**).

The WDT timer and postscaler are cleared by executing a SLEEP or CLRWDT instruction, the loss of a currently selected clock source (if the Fail-Safe Clock Monitor is enabled) and modifying the IRCF bits in the OSCCON register if the internal oscillator block is the device clock source.

4.5.3 EXIT BY RESET

Normally, the device is held in Reset by the Oscillator Start-up Timer (OST) until the primary clock becomes ready. At that time, the OSTS bit is set and the device begins executing code. If the internal oscillator block is the new clock source, the IOFS bit is set instead.

The exit delay time from Reset to the start of code execution depends on both the clock sources before and after the wake-up and the type of oscillator if the new clock source is the primary clock. Exit delays are summarized in Table 4-2.

Code execution can begin before the primary clock becomes ready. If either the Two-Speed Start-up (see **Section 20.3 “Two-Speed Start-up”**) or Fail-Safe Clock Monitor (see **Section 20.4 “Fail-Safe Clock Monitor”**) is enabled, the device may begin execution as soon as the Reset source has cleared. Execution is clocked by the INTOSC multiplexer driven by the internal oscillator block. Execution is clocked by the internal oscillator block until either the primary clock becomes ready or a power-managed mode is entered before the primary clock becomes ready; the primary clock is then shut down.

6.0 MEMORY ORGANIZATION

There are three types of memory in PIC18 Enhanced microcontroller devices:

- Program Memory
- Data RAM
- Data EEPROM

As Harvard architecture devices, the data and program memories use separate busses; this allows for concurrent access of the two memory spaces. The data EEPROM, for practical purposes, can be regarded as a peripheral device, since it is addressed and accessed through a set of control registers.

Additional detailed information on the operation of the Flash program memory is provided in **Section 7.0 "Flash Program Memory"**. Data EEPROM is discussed separately in **Section 8.0 "Data EEPROM Memory"**.

6.1 Program Memory Organization

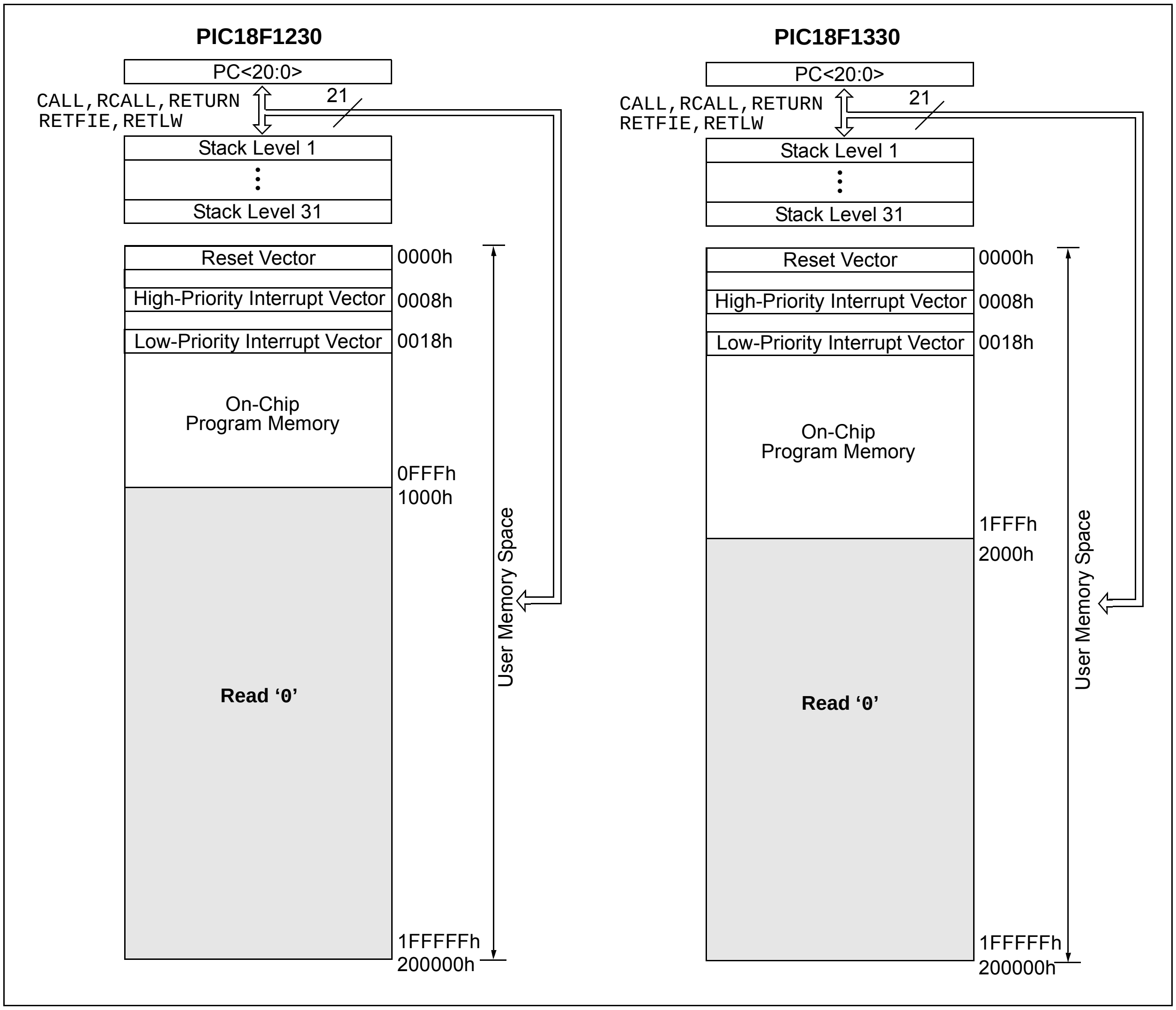
PIC18 microcontrollers implement a 21-bit program counter, which is capable of addressing a 2-Mbyte program memory space. Accessing a location between the upper boundary of the physically implemented memory and the 2-Mbyte address will return all '0's (a NOP instruction).

The PIC18F1230 has 4 Kbytes of Flash memory and can store up to 2,048 single-word instructions. The PIC18F1330 has 8 Kbytes of Flash memory and can store up to 4,096 single-word instructions.

PIC18 devices have two interrupt vectors. The Reset vector address is at 0000h and the interrupt vector addresses are at 0008h and 0018h.

The program memory maps for PIC18F1230 and PIC18F1330 devices are shown in Figure 6-1.

FIGURE 6-1: PROGRAM MEMORY MAP AND STACK FOR PIC18F1230/1330 DEVICES



REGISTER 11-5: PIR2: PERIPHERAL INTERRUPT REQUEST (FLAG) REGISTER 2

R/W-0	U-0	U-0	R/W-0	U-0	R/W-0	U-0	U-0
OSCFIF	—	—	EEIF	—	LVDIF	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **OSCFIF:** Oscillator Fail Interrupt Flag bit
1 = Device oscillator failed, clock input has changed to INTOSC (must be cleared in software)
0 = Device clock operating

bit 6-5 **Unimplemented:** Read as ‘0’

bit 4 **EEIF:** Data EEPROM/Flash Write Operation Interrupt Flag bit
1 = The write operation is complete (must be cleared in software)
0 = The write operation is not complete or has not been started

bit 3 **Unimplemented:** Read as ‘0’

bit 2 **LVDIF:** Low-Voltage Detect Interrupt Flag bit
1 = A low-voltage condition occurred
0 = A low-voltage condition has not occurred

bit 1-0 **Unimplemented:** Read as ‘0’

REGISTER 11-6: PIR3: PERIPHERAL INTERRUPT REQUEST (FLAG) REGISTER 3

U-0	U-0	U-0	R/W-0	U-0	U-0	U-0	U-0
—	—	—	PTIF	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4 **PTIF:** PWM Time Base Interrupt bit
1 = PWM time base matched the value in PTPER register. Interrupt is issued according to the postscaler settings. PTIF must be cleared in software.
0 = PWM time base has not matched the value in PTPER register

bit 3-0 **Unimplemented:** Read as ‘0’

11.5 RCON Register

The RCON register contains flag bits which are used to determine the cause of the last Reset or wake-up from Idle or Sleep modes. RCON also contains the IPEN bit which enables interrupt priorities.

The operation of the SBOREN bit and the Reset flag bits is discussed in more detail in **Section 5.1 "RCON Register"**.

REGISTER 11-13: RCON: RESET CONTROL REGISTER

R/W-0	R/W-1(1)	U-0	R/W-1	R-1	R-1	R/W-0(2)	R/W-0
IPEN	SBOREN	—	$\overline{\text{RI}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **IPEN:** Interrupt Priority Enable bit
1 = Enable priority levels on interrupts
0 = Disable priority levels on interrupts (PIC16CXXX Compatibility mode)

bit 6 **SBOREN:** BOR Software Enable bit(1)
For details of bit operation, see Register 5-1.

bit 5 **Unimplemented:** Read as '0'

bit 4 **$\overline{\text{RI}}$:** RESET Instruction Flag bit
For details of bit operation, see Register 5-1.

bit 3 **$\overline{\text{TO}}$:** Watchdog Time-out Flag bit
For details of bit operation, see Register 5-1.

bit 2 **$\overline{\text{PD}}$:** Power-Down Detection Flag bit
For details of bit operation, see Register 5-1.

bit 1 **$\overline{\text{POR}}$:** Power-on Reset Status bit(2)
For details of bit operation, see Register 5-1.

bit 0 **$\overline{\text{BOR}}$:** Brown-out Reset Status bit
For details of bit operation, see Register 5-1.

Note 1: If SBOREN is enabled, its Reset state is '1'; otherwise, it is '0'. See Register 5-1 for additional information.

2: The actual Reset value of $\overline{\text{POR}}$ is determined by the type of device Reset. See Register 5-1 for additional information.

14.6 PWM Duty Cycle

PWM duty cycle is defined by the PDCx (PDCxL and PDCxH) registers. There are a total of three PWM Duty Cycle registers for four pairs of PWM channels. The Duty Cycle registers have 14-bit resolution by combining the six LSbs of PDCxH with the 8 bits of PDCxL. PDCx is a double-buffered register used to set the counting period for the PWM time base.

14.6.1 PWM DUTY CYCLE REGISTERS

There are three 14-bit Special Function Registers used to specify duty cycle values for the PWM module:

- PDC0 (PDC0L and PDC0H)
- PDC1 (PDC1L and PDC1H)
- PDC2 (PDC2L and PDC2H)

The value in each Duty Cycle register determines the amount of time that the PWM output is in the active state. The upper 12 bits of PDCx hold the actual duty cycle value from PTMRH/L<11:0>, while the lower two bits control which internal Q clock the duty cycle match will occur. This 2-bit value is decoded from the Q clocks, as shown in Figure 14-11, when the prescaler is 1:1 (PTCKPS<1:0> = `00`).

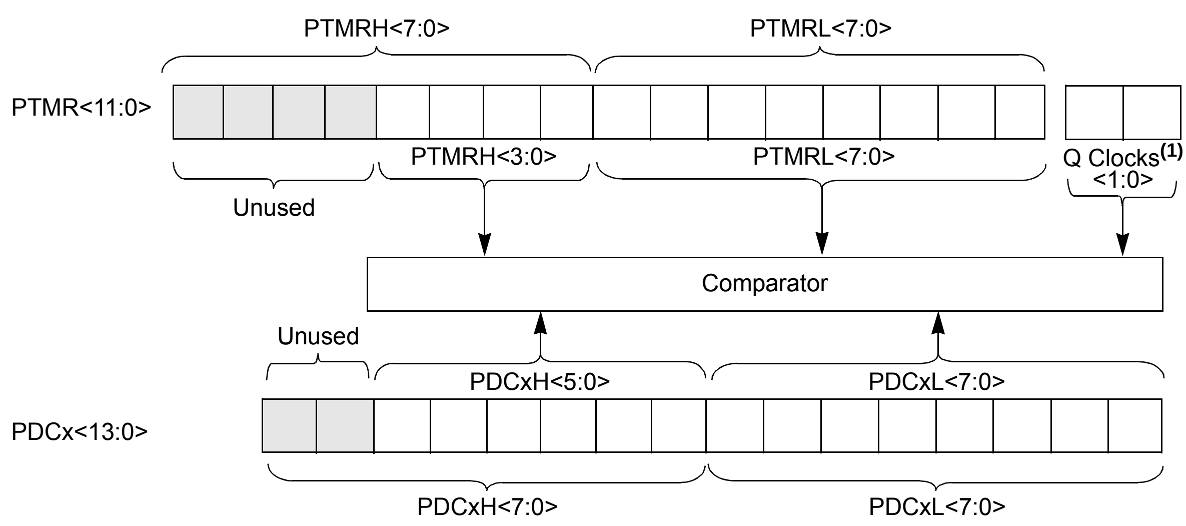
In Edge-Aligned mode, the PWM period starts at Q1 and ends when the Duty Cycle register matches the PTMR register as follows. The duty cycle match is considered when the upper 12 bits of the PDCx are equal to the PTMR and the lower 2 bits are equal to Q1, Q2, Q3 or Q4, depending on the lower two bits of the PDCx (when the prescaler is 1:1 or PTCKPS<1:0> = `00`).

Note:	When the prescaler is not 1:1 (PTCKPS<1:0> ≠ `~00`), the duty cycle match occurs at the Q1 clock of the instruction cycle when the PTMR and PDCx match occurs.

Each compare unit has logic that allows override of the PWM signals. This logic also ensures that the PWM signals will complement each other (with dead-time insertion) in Complementary mode (see **Section 14.7 "Dead-Time Generators"**).

Note:	To get the correct PWM duty cycle, always multiply the calculated PWM duty cycle value by four before writing it to the PWM Duty Cycle registers. This is due to the two additional LSBs in the PWM Duty Cycle registers which are compared against the internal Q clock for the PWM duty cycle match.

FIGURE 14-11: DUTY CYCLE COMPARISON



Note 1: This value is decoded from the Q clocks:
`00` = duty cycle match occurs on Q1
`01` = duty cycle match occurs on Q2
`10` = duty cycle match occurs on Q3
`11` = duty cycle match occurs on Q4

REGISTER 15-1: TXSTA: TRANSMIT STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-1	R/W-0
CSRC	TX9	TXEN(1)	SYNC	SENDB	BRGH	TRMT	TX9D
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **CSRC:** Clock Source Select bit
Asynchronous mode:
Don’t care.
Synchronous mode:
1 = Master mode (clock generated internally from BRG)
0 = Slave mode (clock from external source)

bit 6 **TX9:** 9-Bit Transmit Enable bit
1 = Selects 9-bit transmission
0 = Selects 8-bit transmission

bit 5 **TXEN:** Transmit Enable bit(1)
1 = Transmit enabled
0 = Transmit disabled

bit 4 **SYNC:** EUSART Mode Select bit
1 = Synchronous mode
0 = Asynchronous mode

bit 3 **SENDB:** Send Break Character bit
Asynchronous mode:
1 = Send Sync Break on next transmission (cleared by hardware upon completion)
0 = Sync Break transmission completed
Synchronous mode:
Don’t care.

bit 2 **BRGH:** High Baud Rate Select bit
Asynchronous mode:
1 = High speed
0 = Low speed
Synchronous mode:
Unused in this mode.

bit 1 **TRMT:** Transmit Shift Register Status bit
1 = TSR empty
0 = TSR full

bit 0 **TX9D:** 9th bit of Transmit Data
Can be address/data bit or a parity bit.

Note 1: SREN/CREN overrides TXEN in Sync mode.

REGISTER 15-3: BAUDCON: BAUD RATE CONTROL REGISTER

R/W-0	R-1	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	—	WUE	ABDEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **ABDOVF**: Auto-Baud Acquisition Rollover Status bit
1 = A BRG rollover has occurred during Auto-Baud Rate Detect mode (must be cleared in software)
0 = No BRG rollover has occurred

bit 6 **RCIDL**: Receive Operation Idle Status bit
1 = Receive operation is Idle
0 = Receive operation is active

bit 5 **RXDTP**: Received Data Polarity Select bit
Asynchronous mode:
1 = RX data is inverted
0 = RX data is not inverted
Synchronous mode:
Unused in this mode.

bit 4 **TXCKP**: Clock and Data Polarity Select bit
Asynchronous mode:
1 = Idle state for transmit (TX) is a low level
0 = Idle state for transmit (TX) is a high level
Synchronous mode:
1 = Idle state for clock (CK) is a high level
0 = Idle state for clock (CK) is a low level

bit 3 **BRG16:** 16-Bit Baud Rate Register Enable bit
1 = 16-bit Baud Rate Generator – SPBRGH and SPBRG
0 = 8-bit Baud Rate Generator – SPBRG only (Compatible mode), SPBRGH value ignored

bit 2 **Unimplemented:** Read as '0'

bit 1 **WUE:** Wake-up Enable bit
Asynchronous mode:
1 = EUSART will continue to sample the RX pin – interrupt generated on falling edge; bit cleared in hardware on following rising edge
0 = RX pin not monitored or rising edge detected
Synchronous mode:
Unused in this mode.

bit 0 **ABDEN**: Auto-Baud Detect Enable bit
Asynchronous mode:
1 = Enable baud rate measurement on the next character. Requires reception of a Sync field (55h); cleared in hardware upon completion
0 = Baud rate measurement disabled or completed
Synchronous mode:
Unused in this mode.

16.3 Selecting and Configuring Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set. It also gives users the option to use an automatically determined acquisition time.

Acquisition time may be set with the ACQT2:ACQT0 bits (ADCON2<5:3>), which provide a range of 2 to 20 TAD. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

Manual acquisition is selected when ACQT2:ACQT0 = 000. When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This option is also the default Reset state of the ACQT2:ACQT0 bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

16.4 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 11 TAD per 10-bit conversion. The source of the A/D conversion clock is software selectable. There are seven possible options for TAD:

- 2 TOSC
- 4 TOSC
- 8 TOSC
- 16 TOSC
- 32 TOSC
- 64 TOSC
- Internal RC Oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible, but greater than the minimum TAD (see parameter 130 for more information).

Table 16-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 16-1: TAD vs. DEVICE OPERATING FREQUENCIES

AD Clock Source (TAD)		Maximum Device Frequency	
Operation	ADCS2:ADCS0	PIC18F1230/1330	PIC18LF1230/1330(4)
2 TOSC	000	2.86 MHz	1.43 MHz
4 TOSC	100	5.71 MHz	2.86 MHz
8 TOSC	001	11.43 MHz	5.72 MHz
16 TOSC	101	22.86 MHz	11.43 MHz
32 TOSC	010	40.0 MHz	22.86 MHz
64 TOSC	110	40.0 MHz	22.86 MHz
RC(3)	x11	1.00 MHz(1)	1.00 MHz(2)

Note 1: The RC source has a typical TAD time of 1.2 μs.

2: The RC source has a typical TAD time of 2.5 μs.

3: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or the A/D accuracy may be out of specification.

4: Low-power (PIC18LF1230/1330) devices only.

18.0 COMPARATOR VOLTAGE REFERENCE MODULE

The comparator voltage reference is a 16-tap resistor ladder network that provides a selectable reference voltage. Its purpose is to provide a reference for the analog comparators.

A block diagram of the module is shown in Figure 18-1. The resistor ladder is segmented to provide two ranges of CVREF values and has a power-down function to conserve power when the reference is not being used. The module's supply reference can be provided from either device VDD/VSS or an external voltage reference.

18.1 Configuring the Comparator Voltage Reference

The voltage reference module is controlled through the CVRCON register (Register 18-1). The comparator voltage reference provides two ranges of output voltage, each with 16 distinct levels. The range to be used is selected by the CVRR bit (CVRCON<5>). The primary difference between the ranges is the size of the steps selected by the CVREF selection bits (CVR3:CVR0), with one range offering finer resolution. The equations used to calculate the output of the comparator voltage reference are as follows:

If CVRR = `1`:
CVREF = ((CVR3:CVR0)/24) x CVRSRC

If CVRR = `0`:
CVREF = (CVRSRC x 1/4) + (((CVR3:CVR0)/32) x CVRSRC)

The comparator reference supply voltage can come from either AVDD or AVSS, or the external VREF+ that is multiplexed with RA4 and AVSS. The voltage source is selected by the CVRSS bit (CVRCON<4>).

Additionally, the voltage reference can select the unscaled VREF+ input for use by the comparators, bypassing the CVREF module. (See Table 18-1 and Figure 18-1.)

The settling time of the comparator voltage reference must be considered when changing the CVREF output (see Table 23-3 in **Section 23.0 "Electrical Characteristics"**).

TABLE 18-1: VOLTAGE REFERENCE OUTPUT

CVREN	CVRSS	CVREF	Comparator Input
0	0	Disabled	No reference
0	1	Disabled	From VREF (CVREF bypassed)
1	0	Enabled	From CVREF
1	1	Enabled	From CVREF

REGISTER 20-15: WDTCON: WATCHDOG TIMER CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	SWDTEN(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-1 **Unimplemented:** Read as ‘0’

bit 0 **SWDTEN:** Software Controlled Watchdog Timer Enable bit(1)
1 = Watchdog Timer is on
0 = Watchdog Timer is off

Note 1: This bit has no effect if the Configuration bit, WDTEN, is enabled.

TABLE 20-2: SUMMARY OF WATCHDOG TIMER REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
RCON	IPEN	SBOREN(1)	—	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	48
WDTCON	—	—	—	—	—	—	—	SWDTEN(2)	48

Legend: — = unimplemented, read as ‘0’. Shaded cells are not used by the Watchdog Timer.

Note 1: The SBOREN bit is only available when the BOREN1:BOREN0 Configuration bits = 01; otherwise, it is disabled and reads as ‘0’. See **Section 5.4 “Brown-out Reset (BOR)”**.

2: This bit has no effect if the Configuration bit, WDTEN, is enabled.

DECFSZ — Decrement f, Skip if 0

Syntax: DECFSZ f {,d {,a}}

Operands: $0 \le f \le 255$
d ∈ [0,1]
a ∈ [0,1]

Operation: (f) – 1 → dest,
skip if result = 0

Status Affected: None

Encoding:

0010	11da	ffff	ffff

Description: The contents of register ‘f’ are decremented. If ‘d’ is ‘0’, the result is placed in W. If ‘d’ is ‘1’, the result is placed back in register ‘f’.
If the result is ‘0’, the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a two-cycle instruction.
If ‘a’ is ‘0’, the Access Bank is selected. If ‘a’ is ‘1’, the BSR is used to select the GPR bank.
If ‘a’ is ‘0’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 22.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:

```
HERE      DECFSZ   CNT, 1, 1
          GOTO     LOOP
CONTINUE
```

Before Instruction
PC = Address (HERE)
After Instruction
CNT = CNT – 1
If CNT = 0;
PC = Address (CONTINUE)
If CNT ≠ 0;
PC = Address (HERE + 2)

DCFSNZ — Decrement f, Skip if Not 0

Syntax: DCFSNZ f {,d {,a}}

Operands: $0 \le f \le 255$
d ∈ [0,1]
a ∈ [0,1]

Operation: (f) – 1 → dest,
skip if result ≠ 0

Status Affected: None

Encoding:

0100	11da	ffff	ffff

Description: The contents of register ‘f’ are decremented. If ‘d’ is ‘0’, the result is placed in W. If ‘d’ is ‘1’, the result is placed back in register ‘f’.
If the result is not ‘0’, the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a two-cycle instruction.
If ‘a’ is ‘0’, the Access Bank is selected. If ‘a’ is ‘1’, the BSR is used to select the GPR bank.
If ‘a’ is ‘0’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 22.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:

```
HERE    DCFSNZ  TEMP, 1, 0
ZERO    :
NZERO   :
```

Before Instruction
TEMP = ?
After Instruction
TEMP = TEMP – 1
If TEMP = 0;
PC = Address (ZERO)
If TEMP ≠ 0;
PC = Address (NZERO)

INCFSZ — Increment f, Skip if 0

Syntax:	INCFSZ f {,d {,a}}
Operands:	$0 \le f \le 255$ $d \in [0,1]$ $a \in [0,1]$
Operation:	(f) + 1 → dest, skip if result = 0
Status Affected:	None
Encoding:	`0011` `11da` `ffff` `ffff`
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f'. If the result is '0', the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a two-cycle instruction. If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank. If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 22.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.
Words:	1
Cycles:	1(2) **Note:** 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:

```
HERE    INCFSZ   CNT, 1, 0
NZERO   :
ZERO    :
```

Before Instruction
PC = Address (HERE)
After Instruction
CNT = CNT + 1
If CNT = 0;
PC = Address (ZERO)
If CNT ≠ 0;
PC = Address (NZERO)

INFSNZ — Increment f, Skip if Not 0

Syntax:	INFSNZ f {,d {,a}}
Operands:	$0 \le f \le 255$ $d \in [0,1]$ $a \in [0,1]$
Operation:	(f) + 1 → dest, skip if result ≠ 0
Status Affected:	None
Encoding:	`0100` `10da` `ffff` `ffff`
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f'. If the result is not '0', the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a two-cycle instruction. If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank. If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 22.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.
Words:	1
Cycles:	1(2) **Note:** 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:

```
HERE    INFSNZ  REG, 1, 0
ZERO
NZERO
```

Before Instruction
PC = Address (HERE)
After Instruction
REG = REG + 1
If REG ≠ 0;
PC = Address (NZERO)
If REG = 0;
PC = Address (ZERO)

23.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

Ambient temperature under bias .... -40°C to +125°C
Storage temperature .... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD} and $\overline{MCLR}$) .... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} .... -0.3V to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** .... 0V to +13.25V
Total power dissipation **(Note 1)** 1.0W
Maximum current out of V_{SS} pin .... 300 mA
Maximum current into V_{DD} pin .... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) .... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) .... ±20 mA
Maximum output current sunk by any I/O pin .... 25 mA
Maximum output current sourced by any I/O pin .... 25 mA
Maximum current sunk by all ports .... 200 mA
Maximum current sourced by all ports .... 200 mA

Note 1: Power dissipation is calculated as follows:
Pdis = V_{DD} x {I_{DD} – $\sum I_{OH}$} + $\sum$ {(V_{DD} – V_{OH}) x I_{OH}} + $\sum$(V_{OL} x I_{OL})

2: Voltage spikes below V_{SS} at the $\overline{MCLR}$/V_{PP}/RA5/$\overline{FLTA}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{MCLR}$/V_{PP}/RA5/$\overline{FLTA}$ pin, rather than pulling this pin directly to V_{SS}.

† **NOTICE:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

23.2 DC Characteristics: Power-Down and Supply Current PIC18F1230/1330 (Industrial) PIC18LF1230/1330 (Industrial) (Continued)

PIC18LF1230/1330 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F1230/1330 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2)						
	PIC18LF1230/1330	0.8	1.83	mA	-40°C	VDD = 2.0V	FOSC = 4 MHz (**RC_RUN** mode, INTOSC source)
		0.8	1.83	mA	+25°C		
		0.8	1.83	mA	+85°C		
	PIC18LF1230/1330	1.3	2.93	mA	-40°C	VDD = 3.0V	
		1.3	2.93	mA	+25°C		
		1.3	2.93	mA	+85°C		
	All devices	2.5	4.73	mA	-40°C	VDD = 5.0V	
		2.5	4.73	mA	+25°C		
		2.5	4.73	mA	+85°C		
	Extended devices only	2.5	10.0	mA	+125°C		
	PIC18LF1230/1330	2.9	7.6	μA	-40°C	VDD = 2.0V	FOSC = 31 kHz (**RC_IDLE** mode, INTRC source)
		3.1	7.6	μA	+25°C		
		3.6	10.6	μA	+85°C		
	PIC18LF1230/1330	4.5	10.6	μA	-40°C	VDD = 3.0V	
		4.8	10.6	μA	+25°C		
		5.8	14.6	μA	+85°C		
	All devices	9.2	15.6	μA	-40°C	VDD = 5.0V	
		9.8	15.6	μA	+25°C		
		11.4	35.6	μA	+85°C		
	Extended devices only	21	179	μA	+125°C		

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;
MCLR = VDD; WDT enabled/disabled as specified.

3: Low-power Timer1 oscillator selected.

4: BOR and LVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

23.2 DC Characteristics: Power-Down and Supply Current PIC18F1230/1330 (Industrial) PIC18LF1230/1330 (Industrial) (Continued)

PIC18LF1230/1330 (Industrial)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for industrial
PIC18F1230/1330 (Industrial, Extended)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for industrial -40°C ≤ T_A ≤ +125°C for extended

Param No.	Device	Typ	Max	Units	Conditions		
	Module Differential Currents (ΔI_{WDT}, ΔI_{BOR}, ΔI_{LVD}, ΔI_{OSCB}, ΔI_{AD})						
D022 (ΔI_{WDT})	**Watchdog Timer**	1.3	4.8	μA	-40°C	V_{DD} = 2.0V	
		1.4	5.4	μA	+25°C		
		2.0	5.4	μA	+85°C		
		1.9	5.6	μA	-40°C	V_{DD} = 3.0V	
		2.0	6.2	μA	+25°C		
		2.8	6.2	μA	+85°C		
		4.0	9.6	μA	-40°C	V_{DD} = 5.0V	
		5.5	9.6	μA	+25°C		
		5.6	9.6	μA	+85°C		
		13	13	μA	+125°C		
D022A (ΔI_{BOR})	**Brown-out Reset**(4)	35	54.6	μA	-40°C to +85°C	V_{DD} = 3.0V	
		40	64.6	μA	-40°C to +85°C	V_{DD} = 5.0V	
		55	44	μA	-40°C to +125°C		
		0	44	μA	-40°C to +85°C		Sleep mode, BOREN1:BOREN0 = `10`
		0	44	μA	-40°C to +125°C		
D022B (ΔI_{LVD})	**Low-Voltage Detect**(4)	22	37.6	μA	-40°C to +85°C	V_{DD} = 2.0V	
		25	39.6	μA	-40°C to +85°C	V_{DD} = 3.0V	
		29	44.6	μA	-40°C to +85°C	V_{DD} = 5.0V	
		30	54.6	μA	-40°C to +125°C		
D025 (ΔI_{OSCB})	**Timer1 Oscillator**	2.1	5.5	μA	-40°C	V_{DD} = 2.0V	32 kHz on Timer1(3)
		1.8	6.1	μA	+25°C		
		2.1	6.1	μA	+85°C		
		2.2	7	μA	-40°C	V_{DD} = 3.0V	32 kHz on Timer1(3)
		2.6	7.6	μA	+25°C		
		2.9	7.6	μA	+85°C		
		3.0	7.6	μA	-40°C	V_{DD} = 5.0V	32 kHz on Timer1(3)
		3.2	7.6	μA	+25°C		
		3.4	7.6	μA	+85°C		

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{DD} or V_{SS} and all features that add delta current disabled (such as WDT, Timer1 oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all I_{DD} measurements in active operation mode are:
$\overline{OSC1}$ = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD} or V_{SS};
$\overline{MCLR}$ = V_{DD}; WDT enabled/disabled as specified.

3: Low-power Timer1 oscillator selected.

4: BOR and LVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

23.2 DC Characteristics: Power-Down and Supply Current PIC18F1230/1330 (Industrial) PIC18LF1230/1330 (Industrial) (Continued)

PIC18LF1230/1330 (Industrial)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F1230/1330 (Industrial, Extended)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**	
	Module Differential Currents (ΔIWDT, ΔIBOR, ΔILVD, ΔIOSCB, ΔIAD)					
D026 (ΔIAD)	**A/D Converter**	1.0	1.6	μA	-40°C to +85°C	VDD = 2.0V	A/D on, not converting
		1.0	1.6	μA	-40°C to +85°C	VDD = 3.0V	
		1.0	1.6	μA	-40°C to +85°C	VDD = 5.0V	
		2.0	7.6	μA	-40°C to +125°C		

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;
MCLR = VDD; WDT enabled/disabled as specified.

3: Low-power Timer1 oscillator selected.

4: BOR and LVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

23.4.2 TIMING CONDITIONS

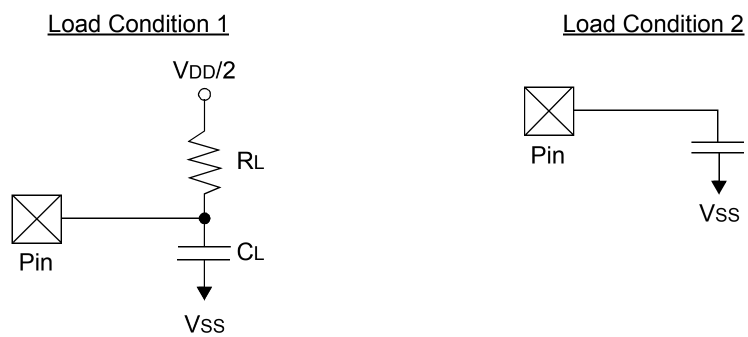
The temperature and voltages specified in Table 23-5 apply to all timing specifications unless otherwise noted. Figure 23-5 specifies the load conditions for the timing specifications.

Note:	Because of space limitations, the generic terms “PIC18FXXXX” and “PIC18LFXXXX” are used throughout this section to refer to the PIC18F1230/1330 and PIC18LF1230/1330 families of devices specifically and only those devices.

TABLE 23-5: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for industrial -40°C ≤ T_A ≤ +125°C for extended Operating voltage V_{DD} range as described in DC spec **Section 23.1** and **Section 23.3**. LF parts operate for industrial temperatures only.

FIGURE 23-5: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



R_L = 464Ω

C_L = 50 pF for all pins except OSC2/CLKO and including D and E outputs as ports

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (November 2005)

Original data sheet for PIC18F1230/1330 devices.

Revision B (February 2006)

Data bank information was updated and a note was added for calculating the PCPWM duty cycle.

Revision C (March 2007)

Updated **Section 23.0 "Electrical Characteristics"** and **Section 24.0 "Packaging Information"**.

Revision D (November 2009)

Updated LIN 1.2 to LIN/J2602 throughout document along with minor corrections throughout document. Added the PIC18LF1230 and PIC18LF1330 devices. Refer to Table A-1 for additional revision history.

TABLE A-1: SECTION REVISION HISTORY

Section Name	Update Description
Section 1.0 "Device Overview"	Updated Table 1-2
Section 6.0 "Memory Organization"	Updated Table 6-2
Section 7.0 "Flash Program Memory"	Updated **Section 7.2.4 "Table Pointer Boundaries"**, Figure 7-3
Section 8.0 "Data EEPROM Memory"	Updated **Section 8.2 "EECON1 and EECON2 Registers"**, **Section 8.8 "Using the Data EEPROM"**
Section 10.0 "I/O Ports"	Updated **Section 10.2 "PORTB, TRISB and LATB Registers"**
Section 14.0 "Power Control PWM Module"	Updated Register 14-6, **Section 14.11.2 "Output Polarity Control"**
Section 15.0 "Enhanced Universal Synchronous Asynchronous Receiver Transmitter (EUSART)"	Updated Register 15-3, **Section 15.1 "Baud Rate Generator (BRG)"**, Table 15-2, **Section 15.1.3 "Auto-Baud Rate Detect"**, **Section 15.2 "EUSART Asynchronous Mode"**, Table 15-5, Table 15-6, **Section 15.3 "EUSART Synchronous Master Mode"**, Figure 15-11, Table 15-7, Figure 15-13, Table 15-8, Table 15-9, Table 15-10
Section 16.0 "10-Bit Analog-to-Digital Converter (A/D) Module"	Updated Register 16-2
Section 17.0 "Comparator Module"	Updated Figure 17-2
Section 18.0 "Comparator Voltage Reference Module"	Updated **Section 18.1 "Configuring the Comparator Voltage Reference"**, Register 18-1, Figure 18-1
Section 20.0 "Special Features of the CPU"	Updated Register 20-6, Register 20-13, Register 20-14
Section 22.0 "Instruction Set Summary"	Updated Table 22-2
Section 23.0 "Electrical Characteristics"	Updated Table 23-1, Figure 23-3, Table 23-2, Table 23-3, Table 23-4, Table 23-5, Table 23-6, Table 23-8, Table 23-14, Table 23-15

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